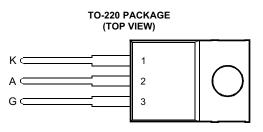
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- 5 A Continuous On-State Current
- 30 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I<sub>GT</sub> of 200 μA



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

#### absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	TIC106D		400	
Repetitive peak off-state voltage (see Note 1)	TIC106M	V	600	V
Repetitive peak off-state voltage (see Note 1)	TIC106S	V <sub>DRM</sub>	700	v
	TIC106N		800	
	TIC106D		400	
	TIC106M	N/	600	V
Repetitive peak reverse voltage	TIC106S	V <sub>RRM</sub>	700	v
	TIC106N		800	
Continuous on-state current at (or below) 80°C case temperature (see Note 2)			5	А
Average on-state current (180° conduction angle) at (or below) 80°C case temperature			3.2	А
(see Note 3)			5.2	A
Surge on-state current (see Note 4)			30	А
Peak positive gate current (pulse width $\leq$ 300 $\mu$ s)			0.2	А
Peak gate power dissipation (pulse width $\leq$ 300 µs)			1.3	W
Average gate power dissipation (see Note 5)			0.3	W
Operating case temperature range			-40 to +110	°C
Storage temperature range			-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds			230	°C

NOTES: 1. These values apply when the gate-cathode resistance  $R_{GK}$  = 1 k $\Omega$ 

- 2. These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.
- This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.

4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

5. This value applies for a maximum averaging time of 20 ms.

#### PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



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PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>D</sub> = rated V <sub>DRM</sub>	$R_{GK}$ = 1 k $\Omega$	T <sub>C</sub> = 110°C			400	μA
I <sub>RRM</sub>	Repetitive peak reverse current	V <sub>R</sub> = rated V <sub>RRM</sub>	I <sub>G</sub> = 0	T <sub>C</sub> = 110°C			1	mA
I <sub>GT</sub>	Gate trigger current	V <sub>AA</sub> = 6 V	R <sub>L</sub> = 100 Ω	$t_{p(g)} \ge 20 \ \mu s$		60	200	μA
V <sub>GT</sub>	Gate trigger voltage	V <sub>AA</sub> = 6 V t <sub>p(g)</sub> ≥ 20 µs	R <sub>L</sub> = 100 Ω R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = - 40°C			1.2	
		V <sub>AA</sub> = 6 V t <sub>p(g)</sub> ≥ 20 µs	R <sub>L</sub> = 100 Ω R <sub>GK</sub> = 1 kΩ		0.4	0.6	1	V
		V <sub>AA</sub> = 6 V t <sub>p(g)</sub> ≥ 20 µs	R <sub>L</sub> = 100 Ω R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = 110°C	0.2			
Ι <sub>Η</sub>	Holding current	$V_{AA} = 6 V$ Initiating I <sub>T</sub> = 10 mA	R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = - 40°C			8	mA
		$V_{AA} = 6 V$ Initiating I <sub>T</sub> = 10 mA	R <sub>GK</sub> = 1 kΩ				5	רעוו
$V_{TM}$	Peak on-state voltage	I <sub>TM</sub> = 5 A	(See Note 6)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	V <sub>D</sub> = rated V <sub>D</sub>	R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = 110°C		10		V/µs

# electrical characteristics at 25°C case temperature (unless otherwise noted)

NOTE 6: This parameter must be measured using pulse techniques, t<sub>p</sub> = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

### thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3.5	°C/W
$R_{\thetaJA}$	Junction to free air thermal resistance			62.5	°C/W

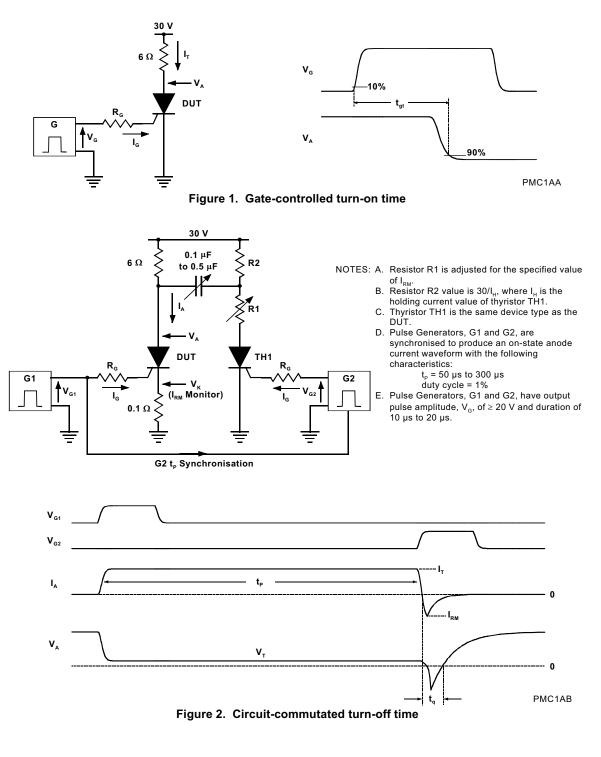
### resistive-load-switching characteristics at 25°C case temperature

PARAMETER		PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
	t <sub>gt</sub>	Gate-controlled turn-on time	I <sub>T</sub> = 5 A	I <sub>G</sub> = 10 mA	See Figure 1		1.75		μs
	t <sub>q</sub>	Circuit-commutated turn-off time	I <sub>T</sub> = 5 A I <sub>RM</sub> = 8 A	I <sub>G</sub> = 10 mA	See Figure 2		7.7		μs

### PRODUCT INFORMATION

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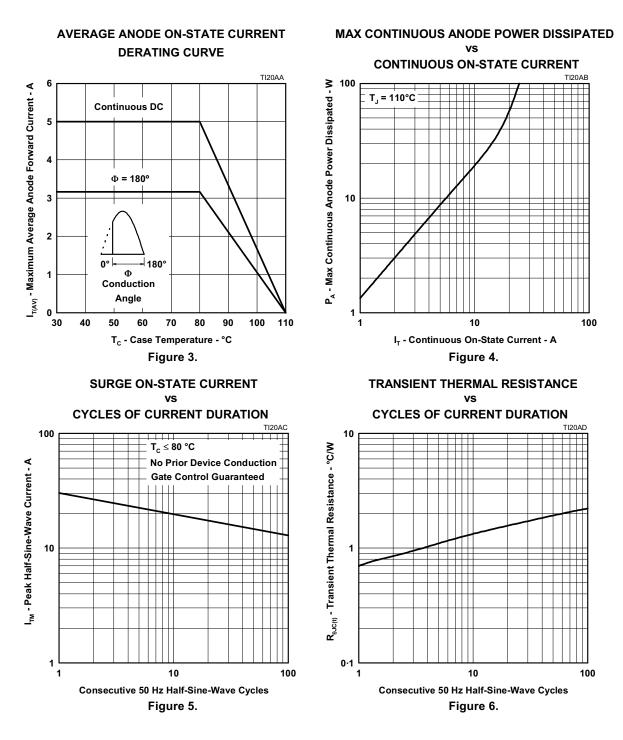




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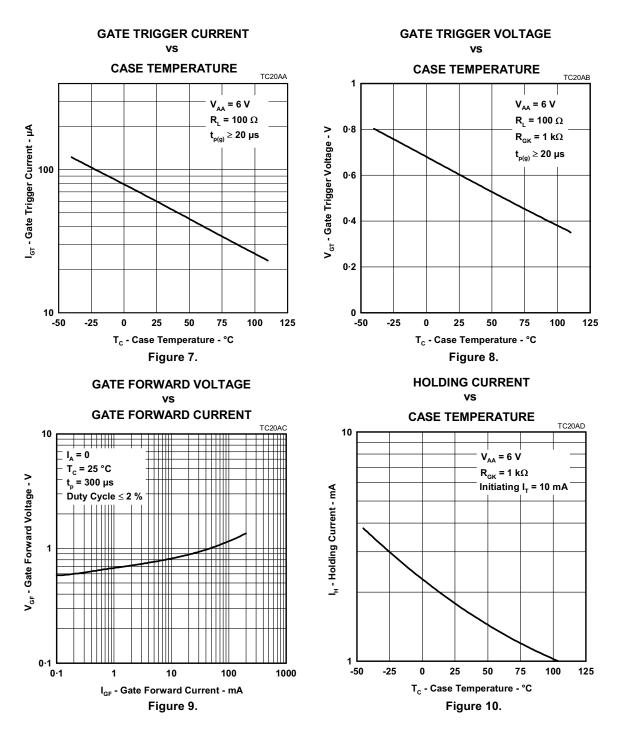
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#### **TYPICAL CHARACTERISTICS**

### PRODUCT INFORMATION

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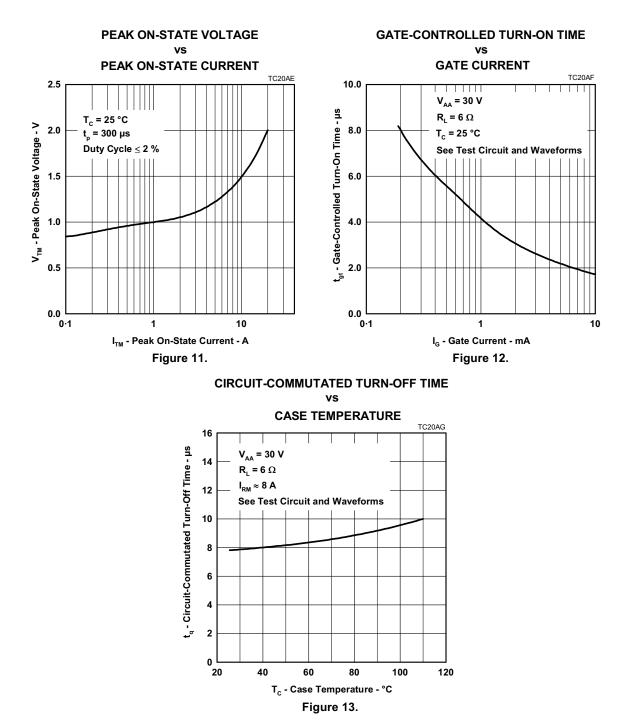


### **TYPICAL CHARACTERISTICS**



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#### **TYPICAL CHARACTERISTICS**

PRODUCT INFORMATION

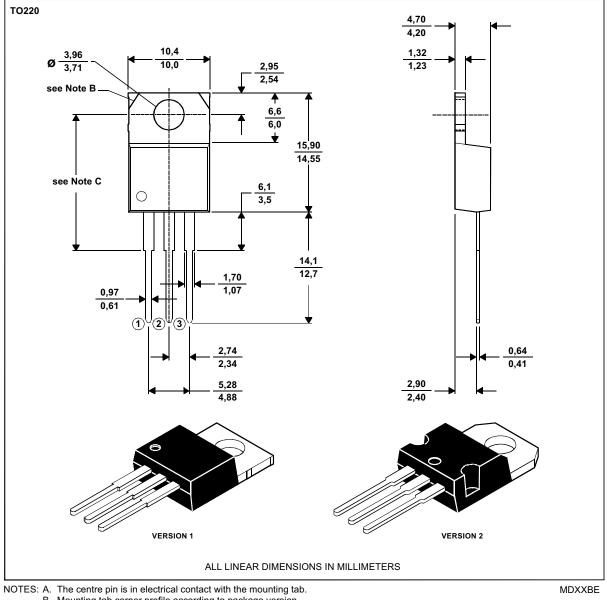
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### **MECHANICAL DATA**

#### **TO-220**

### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



Mounting tab corner profile according to package version. Β.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm.

PRODUCT INFORMATION



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